



Tech-X Announces the Release of USim Version 2.2

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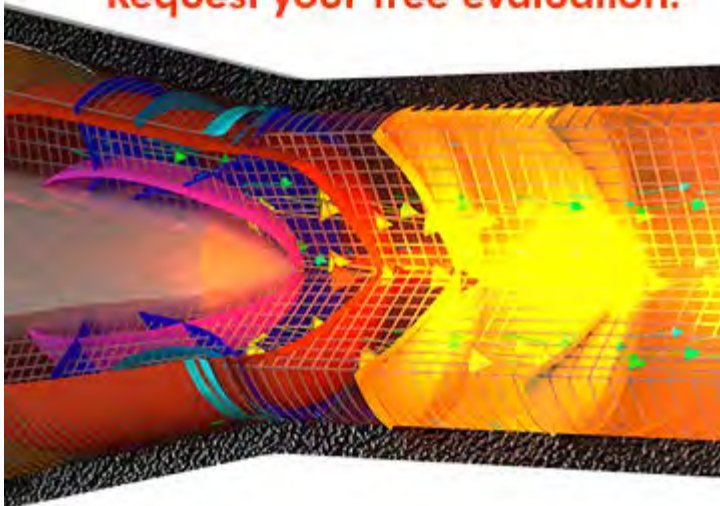
News

[Tech-X Announces the Release of USim Version 2.2](#)

Regular Features

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USim 2.2
Request your free evaluation.



Upcoming Events

April 10-15, 2016: Tech-X Will Exhibit at the 10th European Conference on Antennas and Propagation



Join Tech-X in our booth at [EuCAP](#) in Davos, Switzerland.

April 19-21, 2016: Tech-X Will Exhibit at the 17th

New and Updated Features in [USim 2.2](#)

- Preconditioners for diffusion-type problems.
- Reduced memory footprint for finite volume operators
- Many bug-fixes throughout the simulation engine, documentation and user-interface.

- Improved user interface including better run output, vector plots, and better controls for license

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Simulation Evaluation

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International Vacuum Electronics Conference



Join Tech-X in our booth at [IVEC 2016](#) in Monterey, California.

June 19-23, 2016: Tech-X Will Exhibit at the 43rd International Conference on Plasma Science (ICOPS)



Join Tech-X in our booth at [ICOPS 2016](#) in Banff, Alberta, Canada. On the morning of June 23rd Tech-X will host a meeting presenting a VSim and USim overview, including new VSim version 8 features.